

ECN/PCN No.: 4151

For Manufacturer			
<b>Product Description:</b> PLASTIC SMD MEMS OSCILLATOR	<b>Abracon Part Number / Part Series:</b> EMRE22	<input type="checkbox"/> Documentation only <input type="checkbox"/> ECN <input checked="" type="checkbox"/> EOL	<input checked="" type="checkbox"/> Series <input type="checkbox"/> Part Number
<b>Affected Revision:</b> A	<b>New Revision:</b> EOL	<b>Application:</b> <input type="checkbox"/> Safety <input checked="" type="checkbox"/> Non-Safety	
<b>Prior to Change:</b> Active			
<b>After Change:</b> EOL			
<b>Cause/Reason for Change:</b> Discontinuation of manufacturing capability.			
Change Plan			
<b>Effective Date:</b> 2/7/2022	<b>Additional Remarks:</b> N/A		
<b>Change Declaration:</b> N/A			
<b>Issued Date:</b> 2/7/2022	<b>Issued By:</b> <i>Brooke Cushman</i> Product Engineer	<b>Issued Department:</b> Engineering	
<b>Approval:</b> <i>Thomas Culhane</i> Engineering Director	<b>Approval:</b> <i>Reuben Quintanilla</i> Quality Director	<b>Approval:</b> <i>Ying Huang</i> Purchasing Director	
For Abracon EOL only			
<b>Last Time Buy (if applicable):</b> 5/7/2022	<b>Alternate Part Number / Part Series:</b> AK5 (frequency=100-200MHz), AX5 (frequency greater than 200MHz or less than 100MHz)		
<b>Additional Approval:</b>	<b>Additional Approval:</b>	<b>Additional Approval:</b>	
Customer Approval (If Applicable)			
<b>Qualification Status:</b> <input type="checkbox"/> Approved <input type="checkbox"/> Not accepted <i>Note: It is considered approved if there is no feedback from the customer 1 month after ECN/PCN is released.</i>			
<b>Customer Part Number:</b>		<b>Customer Project:</b>	
<b>Company Name:</b>	<b>Company Representative:</b>	<b>Representative Signature:</b>	
<b>Customer Remarks:</b>			

## REGULATORY COMPLIANCE



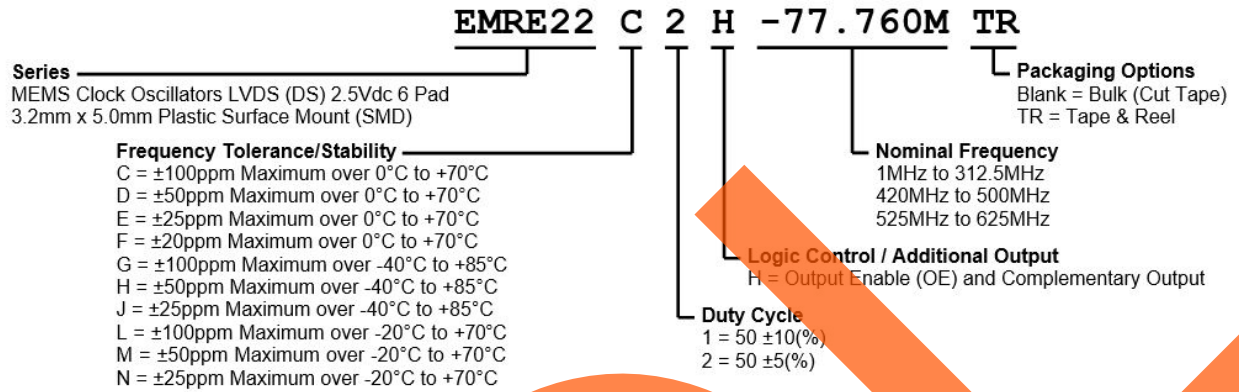
## ITEM DESCRIPTION

MEMS Clock Oscillators LVDS (DS) 2.5Vdc 6 Pad 3.2mm x 5.0mm Plastic Surface Mount (SMD)

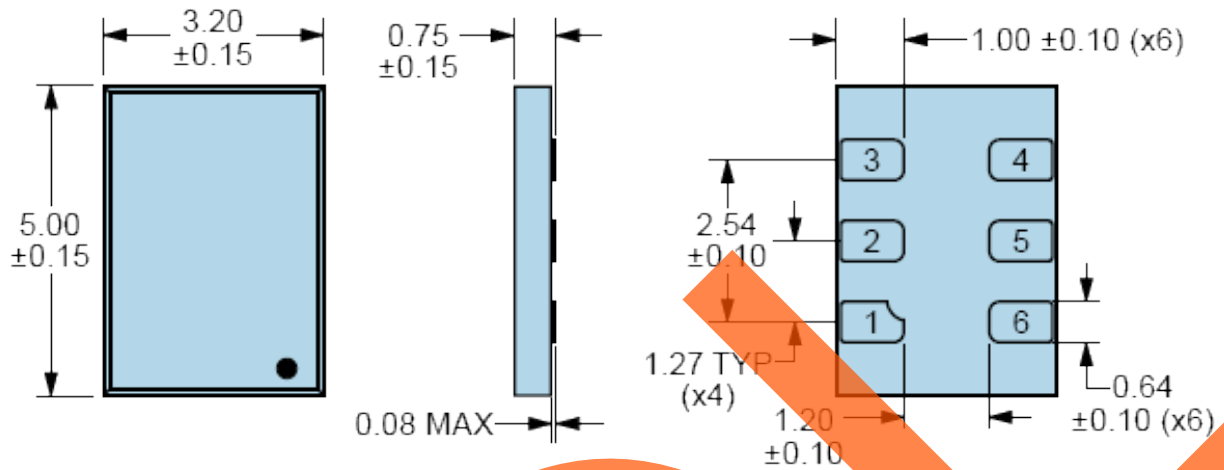
## ELECTRICAL SPECIFICATIONS

Nominal Frequency	1MHz to 625MHz
Frequency Tolerance/Stability	Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, 1st Year Aging at 25°C, Reflow, Shock, and Vibration ±100ppm Maximum over 0°C to +70°C ±50ppm Maximum over 0°C to +70°C ±25ppm Maximum over 0°C to +70°C ±20ppm Maximum over 0°C to +70°C ±100ppm Maximum over -40°C to +85°C ±50ppm Maximum over -40°C to +85°C ±25ppm Maximum over -40°C to +85°C ±100ppm Maximum over -20°C to +70°C ±50ppm Maximum over -20°C to +70°C ±25ppm Maximum over -20°C to +70°C
Aging at 25°C	±1ppm First Year Maximum
Supply Voltage	+2.5Vdc ±10%
Input Current	Excluding Load Termination Current 45mA Typical, 55mA Maximum
Differential Output Voltage (Vod)	200mVdc Minimum, 350mVdc Typical, 500mVdc Maximum
Offset Voltage (Vos)	1.125V Minimum, 1.20V Typical, 1.375V Maximum
Rise/Fall Time	Measured over 20% to 80% of waveform 500pSec Typical, 600pSec Maximum
Differential Output Error (dVod)	50mVdc Maximum
Duty Cycle	Measured at 50% of waveform 50 ±10(%) 50 ±5(%) (Not available with Duty Cycle of 50 ±5(%) over Nominal Frequency range of 312.500001MHz to 524.999999MHz)
Offset Error (dVos)	50mVdc Maximum
Load Drive Capability	100 Ohms Between Output and Complementary Output
Output Logic Type	LVDS
Logic Control / Additional Output	Output Enable (OE) and Complementary Output
Output Control Input Voltage	Vih of 70% of Vdd Minimum or No Connect to Enable Output and Complementary Output, Vil of 30% of Vdd Maximum to Disable Output and Complementary Output (High Impedance)
Output Enable Current	35mA Maximum (Without Load)
RMS Phase Jitter	Fj = 12kHz to 20MHz; Random 0.5pSec Typical, 1pSec Maximum
Period Jitter (Deterministic)	0.2pSec Typical
Period Jitter (Random)	1.0pSec Typical
Period Jitter (RMS)	1.4pSec Typical, 1.7pSec Maximum
Period Jitter (pk-pk)	15pSec Typical, 20pSec Maximum
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to +125°C

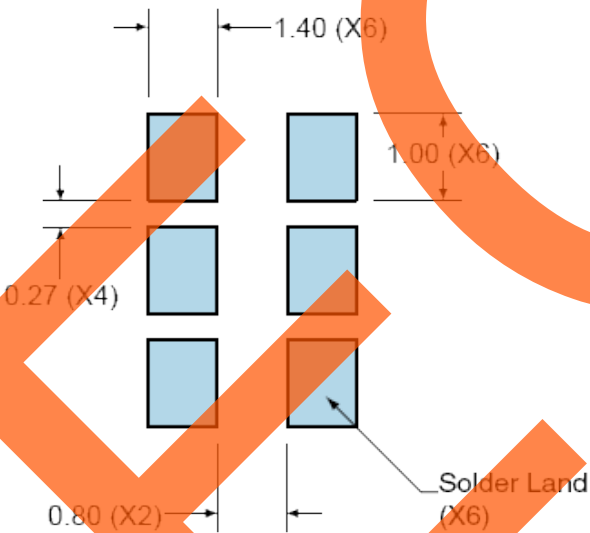
## PART NUMBERING GUIDE



**MECHANICAL DIMENSIONS**



**SUGGESTED SOLDER PAD LAYOUT**

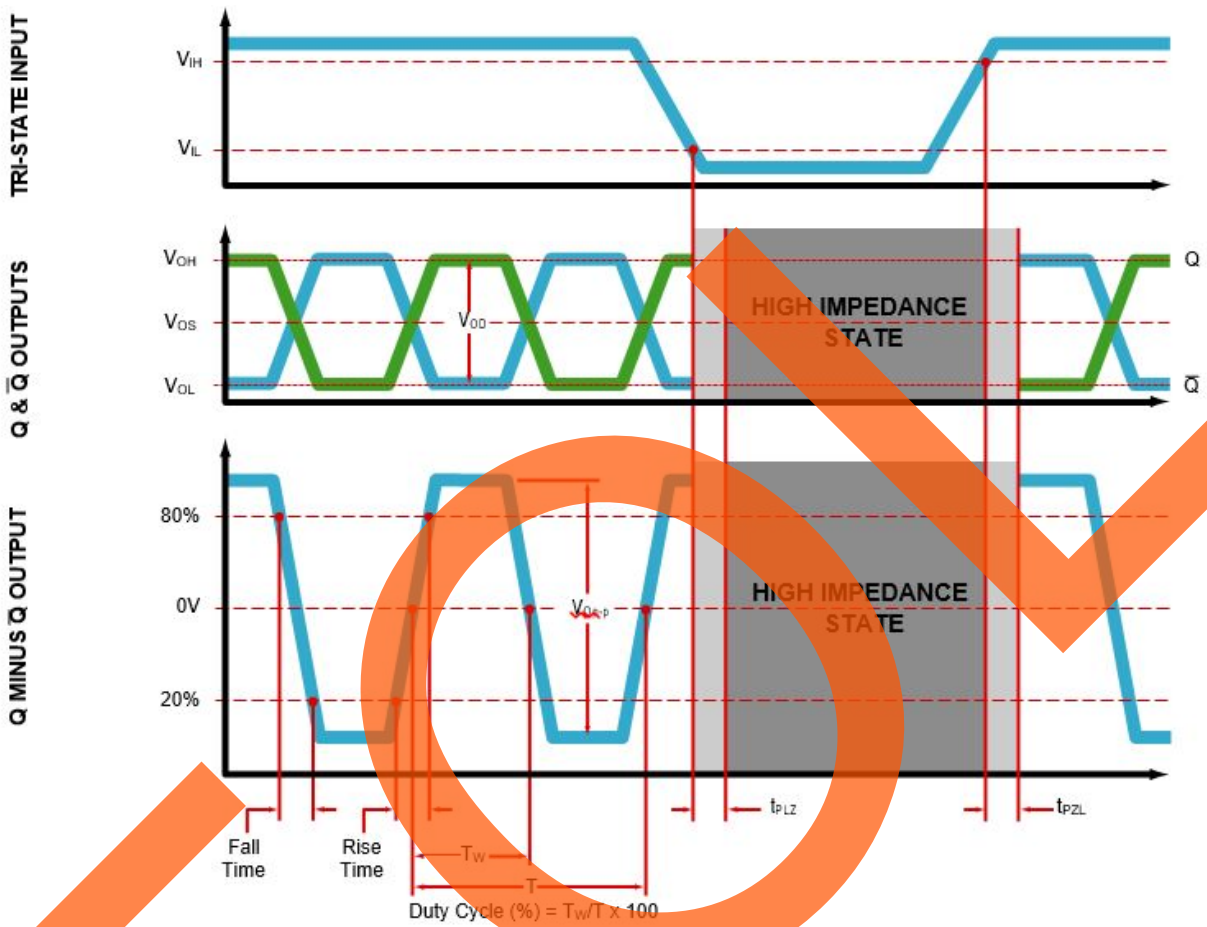


PIN	CONNECTION
1	Output Enable (OE)
2	No Connect
3	Case Ground
4	Output
5	Complementary Output
6	Supply Voltage

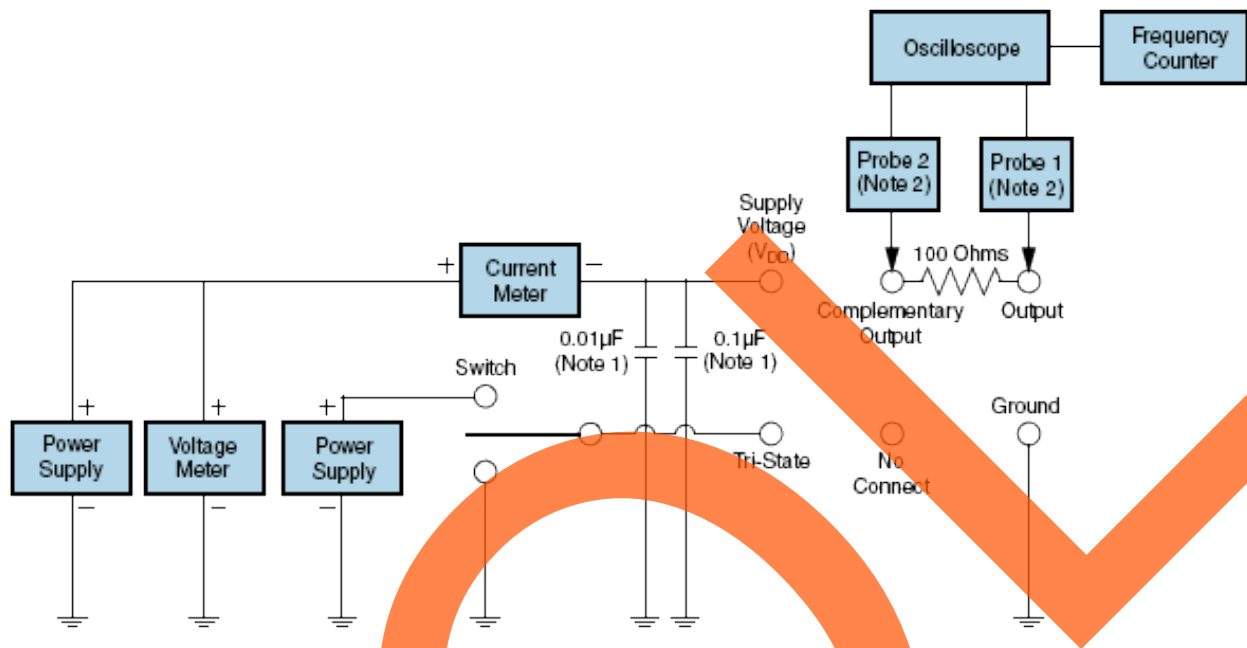
All Tolerances are  $\pm 0.1$

**All Dimensions in Millimeters**

OUTPUT WAVEFORM & TIMING DIAGRAM



## TEST CIRCUIT FOR TRI-STATE AND COMPLEMENTARY OUTPUT



**Note 1:** An external 0.01µF ceramic bypass capacitor in parallel with a 0.1µF high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

**Note 2:** A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>500MHz) passive probe is recommended.

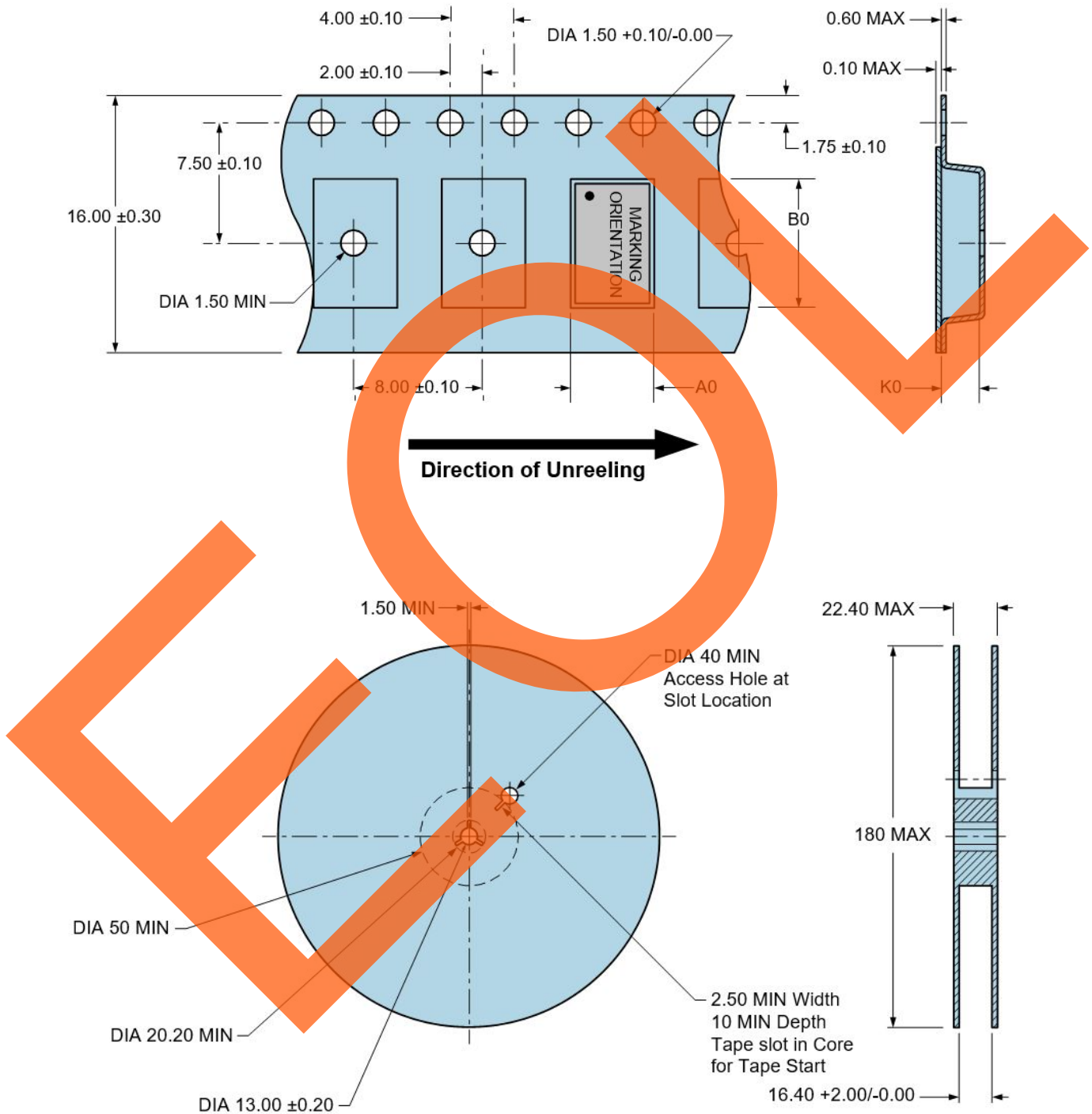
**Note 3:** Test circuit PCB traces need to be designed for a characteristic line impedance of 50 ohms.

**TAPE & REEL DIMENSIONS**

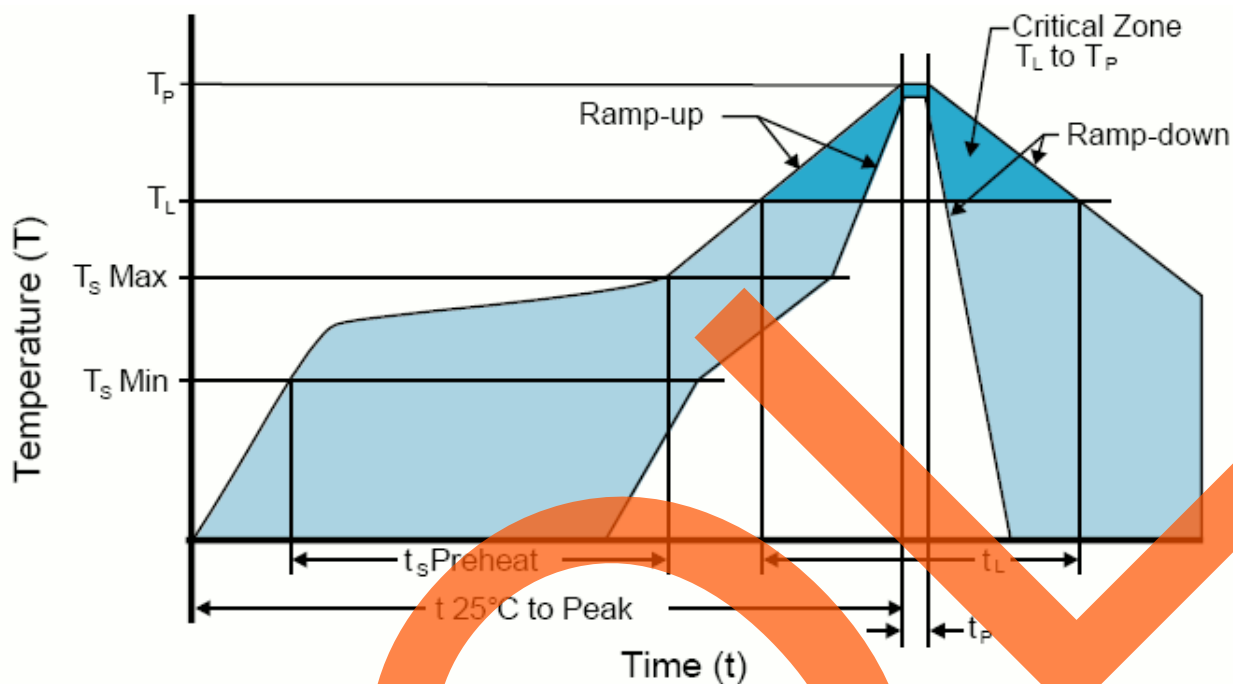
Quantity per Reel: 1,000 Units

All Dimensions in Millimeters

Compliant to EIA-481



RECOMMENDED SOLDER REFLOW METHOD



**HIGH TEMPERATURE INFRARED/CONVECTION**

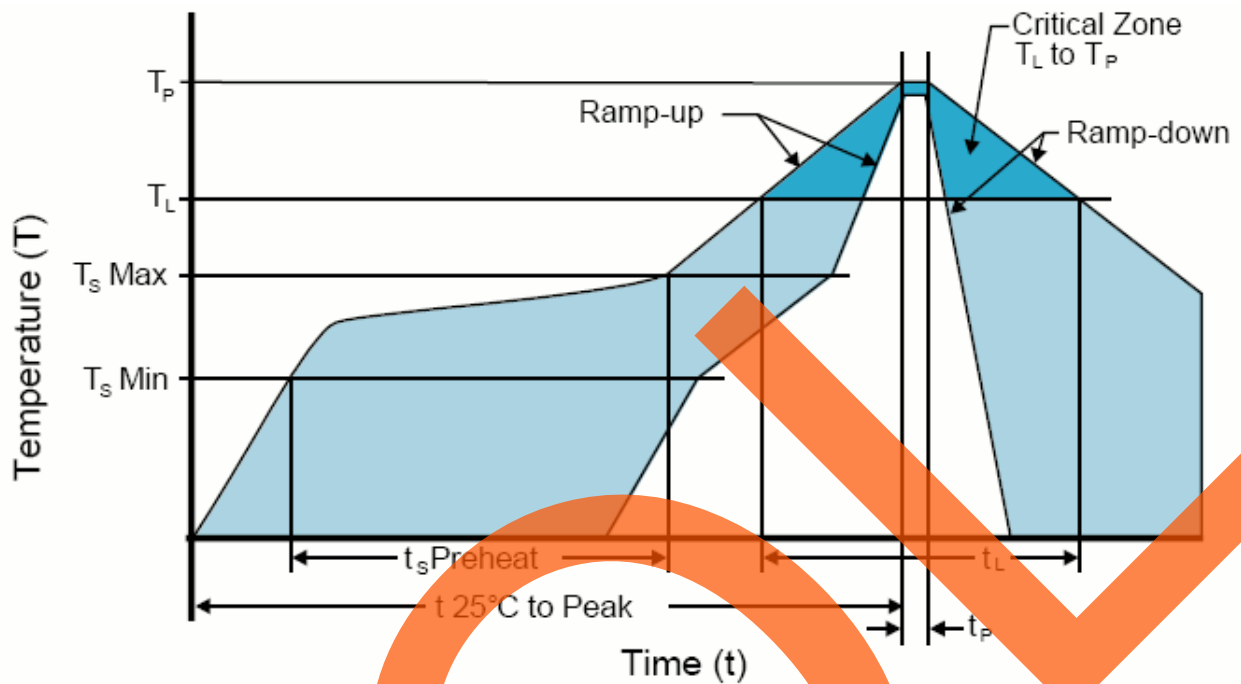
<b>T<sub>S</sub> MAX to T<sub>L</sub> (Ramp-up Rate)</b>	3°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum (T <sub>S</sub> MIN)	150°C
- Temperature Typical (T <sub>S</sub> TYP)	175°C
- Temperature Maximum (T <sub>S</sub> MAX)	200°C
- Time (t <sub>s</sub> MIN)	60 - 180 Seconds
<b>Ramp-up Rate (T<sub>L</sub> to T<sub>P</sub>)</b>	3°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature (T <sub>L</sub> )	217°C
- Time (t <sub>L</sub> )	60 - 150 Seconds
<b>Peak Temperature (T<sub>P</sub>)</b>	260°C Maximum for 10 Seconds Maximum
<b>Target Peak Temperature (T<sub>P</sub> Target)</b>	250°C +0/-5°C
<b>Time within 5°C of actual peak (t<sub>p</sub>)</b>	20 - 40 Seconds
<b>Ramp-down Rate</b>	6°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	8 Minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

**High Temperature Manual Soldering**

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)



RECOMMENDED SOLDER REFLOW METHOD



**LOW TEMPERATURE INFRARED/CONVECTION**

T <sub>S</sub> MAX to T <sub>L</sub> (Ramp-up Rate)	5°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum (T <sub>S</sub> MIN)	N/A
- Temperature Typical (T <sub>S</sub> TYP)	150°C
- Temperature Maximum (T <sub>S</sub> MAX)	N/A
- Time (t <sub>S</sub> MIN)	60 - 120 Seconds
<b>Ramp-up Rate (T<sub>L</sub> to T<sub>P</sub>)</b>	5°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature (T <sub>L</sub> )	150°C
- Time (t <sub>L</sub> )	200 Seconds Maximum
<b>Peak Temperature (T<sub>P</sub>)</b>	240°C Maximum
<b>Target Peak Temperature (T<sub>P</sub> Target)</b>	240°C Maximum 2 Times / 230°C Maximum 1 Time
<b>Time within 5°C of actual peak (t<sub>p</sub>)</b>	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
<b>Ramp-down Rate</b>	5°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	N/A
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

**Low Temperature Manual Soldering**

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)